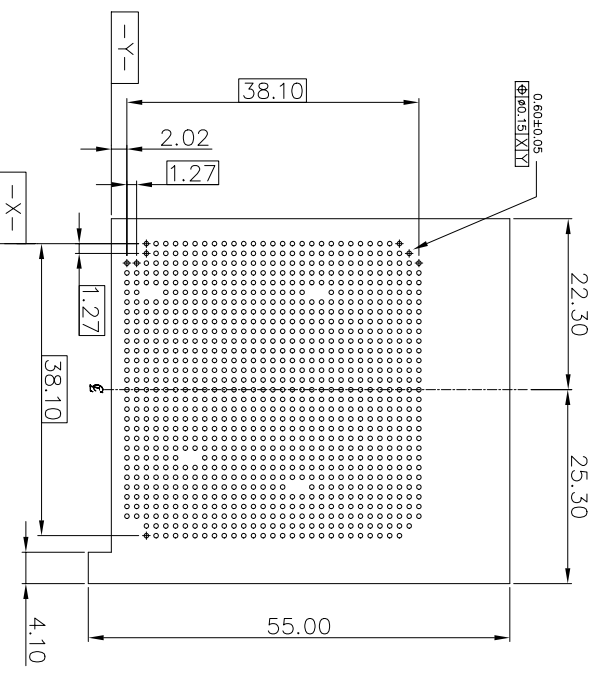
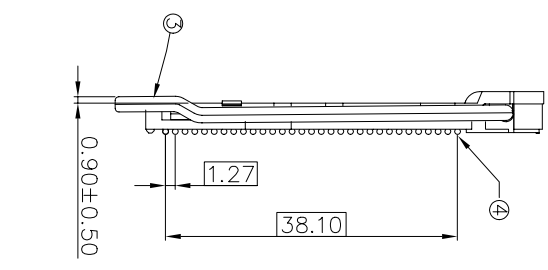
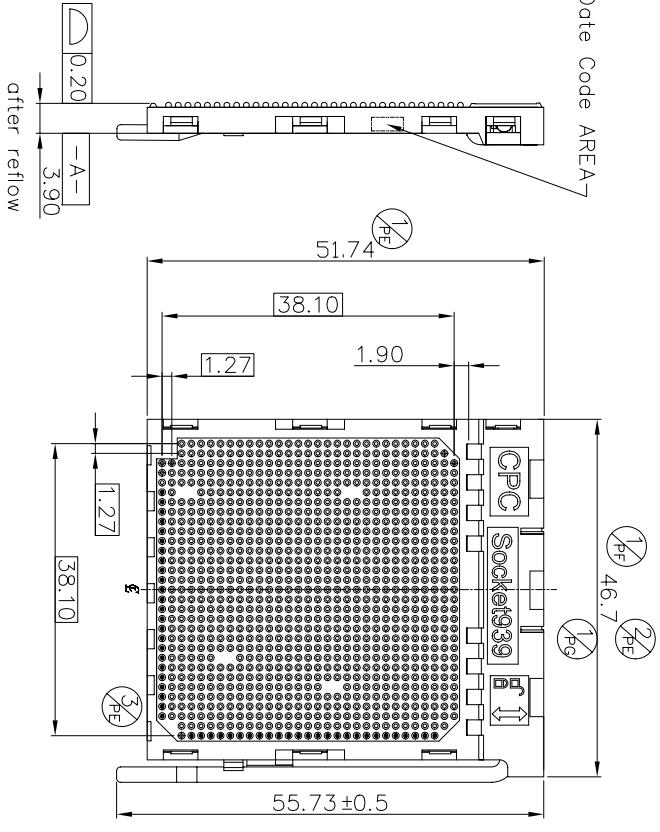




**RoHS Compliant**  
2002/95/EC



Date Code AREA7



RECOMMENDED P.C BOARD LAYOUT

1. 127083FK939JX00PY

- F. Selective plating
- J1-05μ" Min. Gold in contact area.
  - J2-Gold flash in contact area.
  - J3-10μ" Min. Gold in contact area.
  - J4-15μ" Min. Gold in contact area.
  - J5-30μ" Min. Gold in contact area.

5	TERMINAL	Copper Alloy	GOLD PLATED OVER IN
4	Solder Ball	Solder Alloy Composition	
3	HANDLE	Stainless Steel	
2	COVER	High Temp. Plastic	UL 94V-0
1	BASE	High Temp. Plastic	UL 94V-0
NO. DESCRIPTION		MATERIAL	COLOR
		BLACK	REMARK

**SUYIN**  
CONNECTOR SOCKET DEP

CUSTOMER TITLE: Socket 939 Solder Ball Type  
COPY

PART NO. 127083FK939JX00PY

FILE NAME: C 127083FK939JX00PY-C

SCALE: 1:1 UNIT: mm SHEET: 1 of 1

SOCKET DEP 050604-EA014

PG 05/10/06'	結構變更	吳玉明	范政徽	X.	±2°	DRAW	陳葳葳	04/18/05'
PF 04/26/06'	結構變更	吳玉明	范政徽	X.	±0.50	DESIGN	吳玉明	04/18/05'
PE 04/18/06'	結構變更	吳玉明	范政徽	X.X	±0.25	CHECK	范政徽	04/18/05'
PD 11/18/05'	修改標注尺寸	吳玉明	范政徽	X.XX	±0.15	APPRO.	范政徽	04/18/05'
ECN(DCN) NO.	REV	DATE	DESCRIPTION	CHANGE	APPRO.	GENERAL TOLERANCE UNLESS OTHERWISE NOTED		

1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17